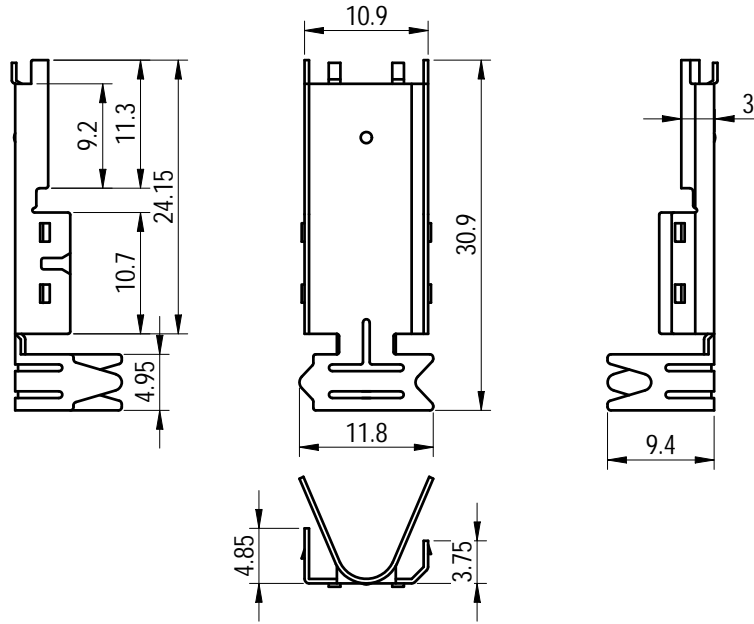
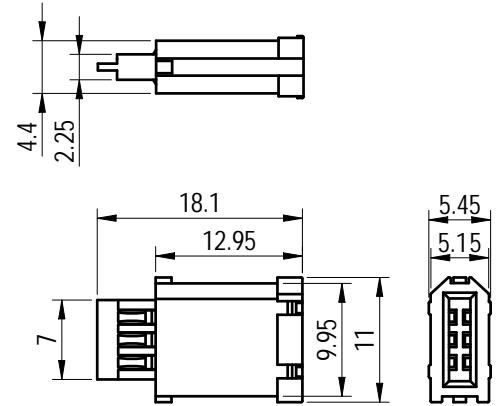


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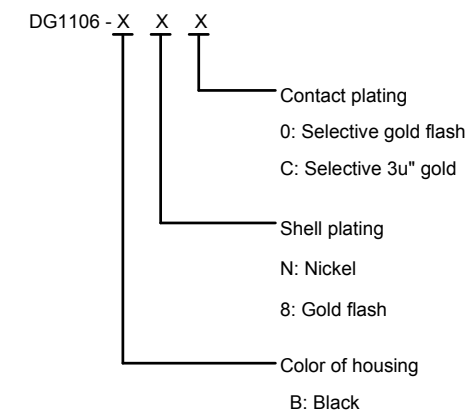


Down shell

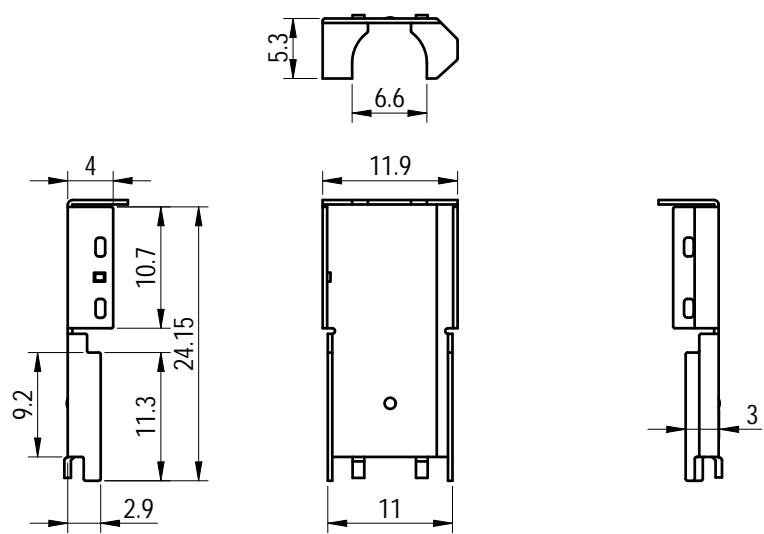


Housing with contact

- NOTES:
- Specifications
    - Contact Resistance: 50mΩ max
    - Insulator Resistance: 100MΩ min.
    - Current Rating: 1.5A per pin max.
    - Rated Voltage: 30V DC
    - Dielectric withstanding voltage: AC 500V For 1 minute
    - Contact: Copper Alloy
    - Housing: Thermoplastic(UL 94V-0)
  - Shell: Steel
  - Product number code:



(Series Image-Reference Only)



Upper shell

|                   |           |            |                |                  |
|-------------------|-----------|------------|----------------|------------------|
| GENERAL TOLERANCE |           |            | MATERIAL:      | SURFACE/COLOR:   |
| X: ±0.60          | X: ±0.38  |            | MAT NO./REV:   | / 00             |
| XX: ±0.25         | APPD: 兰春华 | 2023.08.01 | NAME           |                  |
|                   | CHKD: 陈招  | 2023.08.01 | DG1106-XXX     |                  |
|                   | DRFT: 唐本恒 | 2023.08.01 | DRAWING NO.    | TYPE             |
|                   |           |            | 200035060      | CUSTOMER DRAWING |
|                   |           |            | DRAWING STATUS | SCALE            |
|                   |           |            | 已发布            | 2:1              |
|                   |           |            | SHEET          | 1/1              |

|     |     |             |      |            |
|-----|-----|-------------|------|------------|
| 00  |     |             | 唐本恒  | 2023.08.01 |
| REV | ECN | DESCRIPTION | DRFT | DATE       |